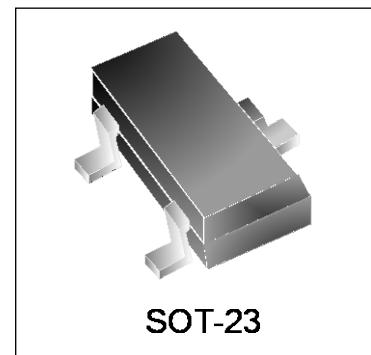


Features

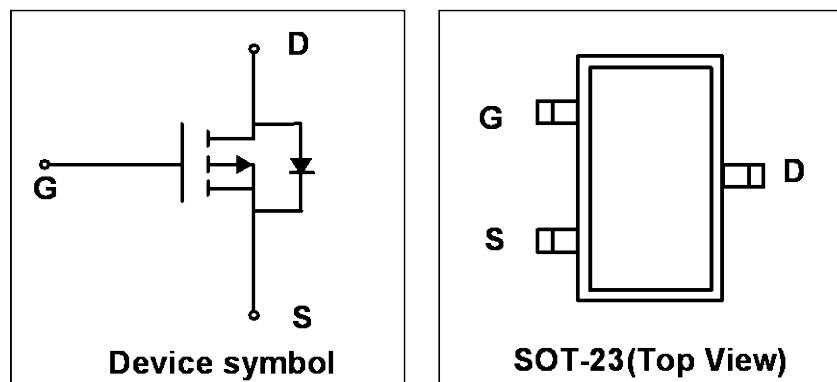
- Way-on Small Signal MOSFETs
- $V_{DS} = -20V$, $I_D = -3A$
 $R_{DS(ON)} < 70m\Omega @ V_{GS} = -4.5V$
 $R_{DS(ON)} < 90m\Omega @ V_{GS} = -2.5V$
- Trench LV MOSFET Technology



Mechanical Characteristics

- SOT-23 Package
- Marking : Making Code
- RoHS Compliant

Schematic & PIN Configuration



Absolute Maximum Rating ($T_A=25^\circ C$ unless otherwise noted)

Rating	Symbol	Value	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current $T_A = 25^\circ C$	I_D	-3	A
Pulsed Drain Current ¹	I_{DM}	-10	A
Power Dissipation $T_A = 25^\circ C$	P_D	1	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Rating	Symbol	Value	Units
Thermal Resistance from Junction to Ambient ²	R_{JA}	125	°C/W

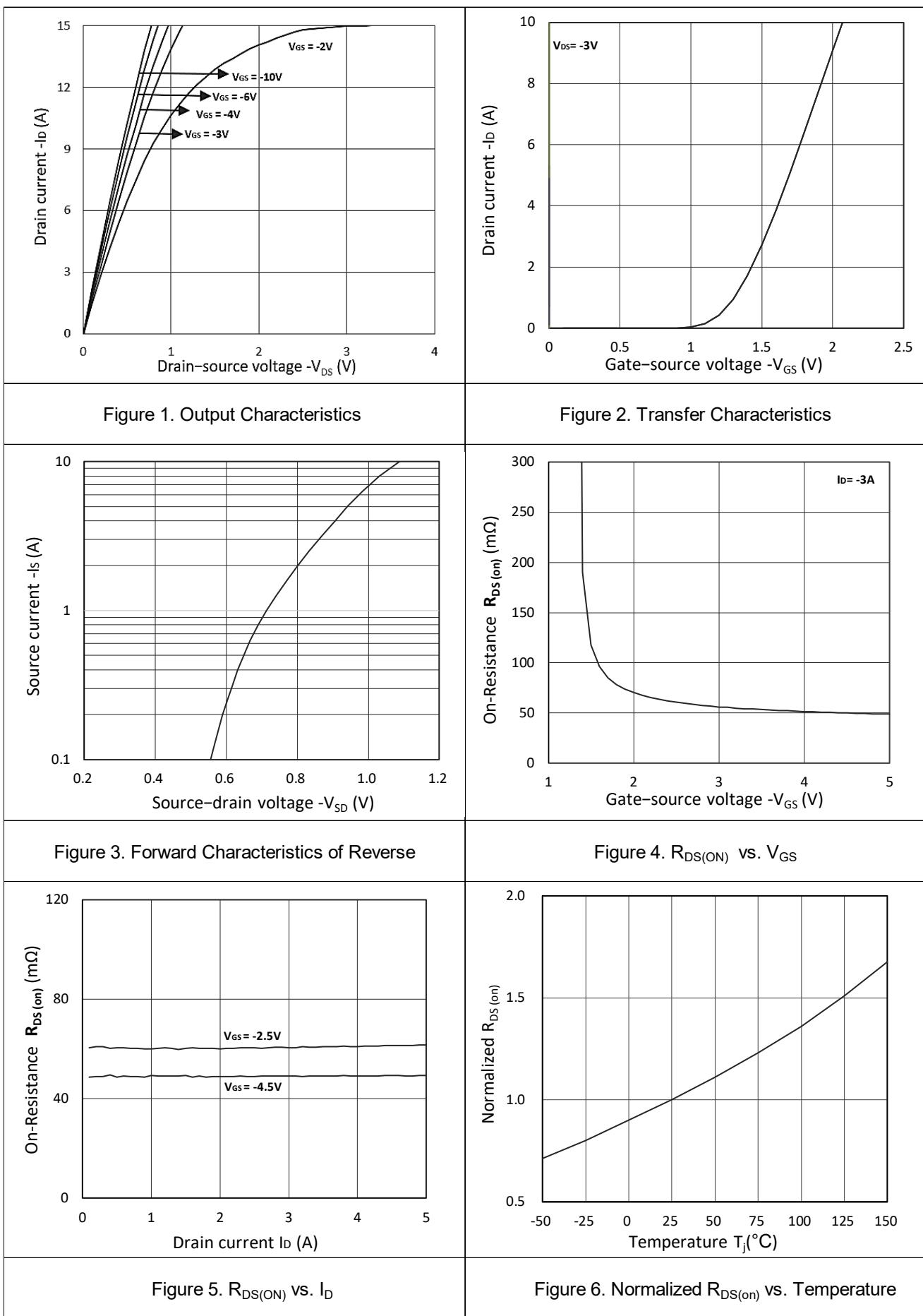
Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V	-	-	-1	μA
Gate-Source Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.4	-	-1	V
Drain-Source on-State Resistance ³	R _{DS(on)}	V _{GS} = -4.5V, I _D = -3.0A	-	50	70	mΩ
		V _{GS} = -2.5V, I _D = -2.0A	-	60	90	
Dynamic Characteristics⁴						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -10V, f=1.0MHz	-	616	-	pF
Output Capacitance	C _{oss}		-	75	-	
Reverse Transfer Capacitance	C _{rss}		-	65	-	
Switching Characteristics⁴						
Total gate charge	Q _g	V _{GS} = -2.5V, V _{DS} = -10V, I _D = -3A	-	3.3	-	nC
Gate-source charge	Q _{gs}		-	0.7	-	
Gate-drain charge	Q _{gd}		-	1.3	-	
Turn-on Time	t _{d(on)}	V _{GS} = -4.5V, V _{DD} = -10V, R _L = 10Ω, R _{GEN} = 1Ω	-	11	-	ns
Rise Time	t _r		-	35	-	
Turn-off Time	t _{d(off)}		-	30	-	
Fall Time	t _f		-	10	-	
Source-Drain Diode Characteristics						
Body Diode Voltage ³	V _{SD}	I _S = -1A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I _S		-	-	-3	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



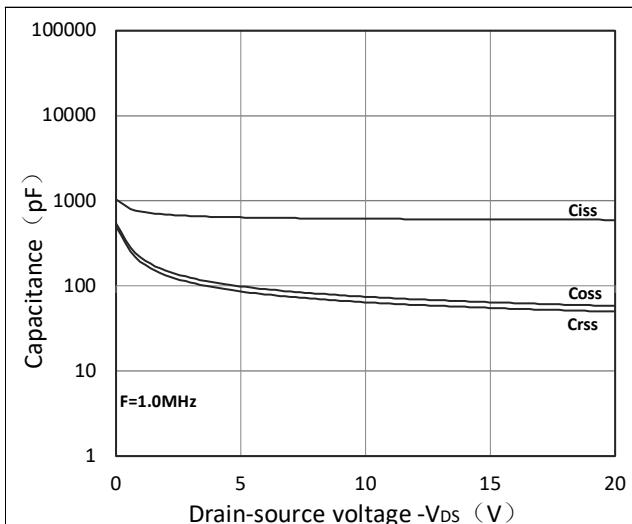


Figure 7. Capacitance Characteristics

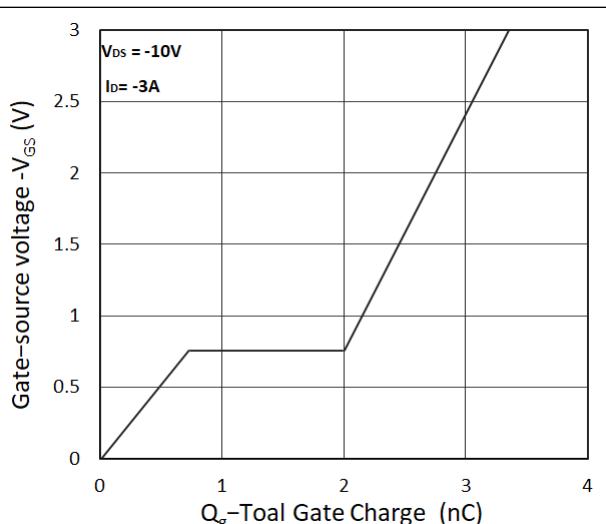
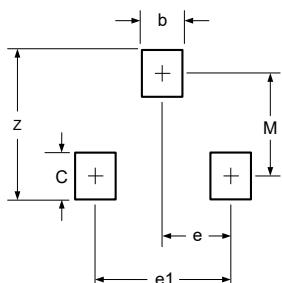
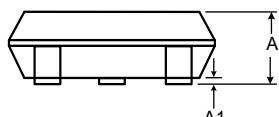
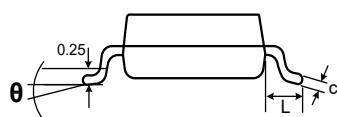
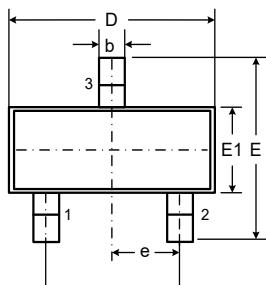


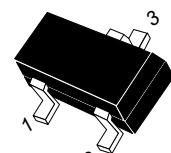
Figure 8. Gate Charge Characteristics

Outline Drawing – SOT-23

PACKAGE OUTLINE



DIMENSIONS		
DIM	INCHES	MILLIMETERS
M	0.080	2.02
C	0.032	0.80
Z	0.111	2.82
e	0.037 BSC	0.95 BSC
e1	0.075 BSC	1.90 BSC
b	0.032	0.80



SOT-23

DIMENSIONS

SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.15	0.035	0.045
A1	0.00	0.10	0.000	0.004
b	0.30	0.50	0.012	0.020
c	0.08	0.15	0.003	0.006
D	2.80	3.00	0.110	0.118
E	2.25	2.55	0.089	0.100
E1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.037BSC	
e1	1.80	2.00	0.071	0.079
L	0.55REF		0.022REF	
θ	0°	8°	0°	8°

Notes

- Dimensioning and tolerances per ANSI Y14.5M, 1985.
- Controlling Dimension: Inches
- Pin 3 is the cathode (Unidirectional Only).
- Dimensions are exclusive of mold flash and metal burrs.

Marking Codes

Part Number	WM02P30M
Marking Code	2301

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.